



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Philip A. Rochette

PATENT APPLICATION

Serial No.: 10/817,619

Group Art Unit: 2811

Filed: April 1, 2004

Examiner:

For: METHOD AND APPARATUS TO ELIMINATE GALVANIC  
CORROSION ON COPPER DOPED ALUMINUM BOND PADS  
ON INTEGRATED CIRCUITS

Supplemental Information Disclosure Statement

Hon. Commissioner for Patents  
Alexandria, VA 22313

Sir:

The following information is submitted in  
compliance with Applicant's duty of disclosure under 37  
CFR § 1.56. A copy of each reference is enclosed.

Other References

S. Thomas et al., "Micro-Corrosion of Al-Cu  
Bonding Pads", IEEE Transactions on Components, Hybrids,  
and Manufacturing Technology, June 1987, Vol. CHMT-10,  
No. 2, pp. 252-257.

Printout: "Galvanic Voids, Semiconductor  
Reliability News, April 1992, 1 page.

CERTIFICATE OF MAILING

I hereby certify that this paper (along with  
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22313

Signed: Sally Azevedo  
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Date: June 30, 2004

Respectfully submitted,

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FORM PTO-1449	Atty. Docket No. ATM-302	Serial No. 10/817,619
LIST OF PRIOR ART CITED BY APPLICANT	Applicant: Philip A. Rochette	
	Filing Date: April 1, 2004	Group: 2811



## U.S. PATENT DOCUMENTS

Examiner Initial*	Document Number	Grant Date	Name	Class	Sub Class	Filing Date
AA						
AB						
AC						
AD						
AE						
AF						
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AH						
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AJ						

## FOREIGN PATENT DOCUMENTS

Examiner Initial*	Document Number	Grant Date	Country	Class	Sub Class	Translation Yes No
AK						
AL						

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

AM	S. Thomas et al., "Micro-Corrosion of Al-Cu Bonding Pads", IEEE Transactions on Components, Hybrids, and Manufacturing Technology, June 1987, Vol. CHMT-10, No. 2, pp. 252-257.
AN	Printout: "Galvanic Voids, Semiconductor Reliability News, April 1992, 1 page.
AO	

EXAMINER:

DATE CONSIDERED:

\*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.